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## The datasheet number will be changing.

Device Family	Change From:	Change To:
UCC28880/ UCC28881	SLUSC05A	SLUSC05C

These changes may be reviewed at the datasheet links provided. <u>http://www.ti.com/product/UCC28880</u>

## **Reason for Change:**

To more accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative): No anticipated impact. This is a specification change announcement only. There are no changes

to the actual device.

## **Changes to product identification resulting from this PCN:**

None.

Product Affected:							
UCC28880D	UCC28880DR	UCC28881D	UCC28881DR				

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

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